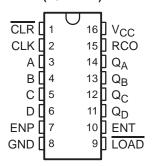
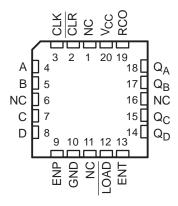
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 14 ns
- ±4-mA Output Drive at 5 V

SN54HC161 . . . J OR W PACKAGE SN74HC161 . . . D, N, NS, OR PW PACKAGE (TOP VIEW)



- Low Input Current of 1 μA Max
- Internal Look-Ahead for Fast Counting
- Carry Output for n-Bit Cascading
- Synchronous Counting
- Synchronously Programmable

SN54HC161 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

These synchronous, presettable counters feature an internal carry look-ahead for application in high-speed counting designs. The 'HC161 devices are 4-bit binary counters. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when so instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes that are normally associated with synchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock waveform.

ORDERING INFORMATION

TA	PACKA	_{GE} †	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – N	Tube of 25	SN74HC161N	SN74HC161N	
		Tube of 40	SN74HC161D		
	SOIC - D	Reel of 2500	SN74HC161DR	HC161	
4000 1- 0500		Reel of 250	SN74HC161DT		
–40°C to 85°C	SOP - NS	Reel of 2000	SN74HC161NSR	HC161	
		Tube of 90	SN74HC161PW		
	TSSOP - PW	Reel of 2000	SN74HC161PWR	HC161	
		Reel of 250	SN74HC161PWT		
	CDIP – J	Tube of 25	SNJ54HC161J	SNJ54HC161J	
-55°C to 125°C	CFP – W	Tube of 150	SNJ54HC161W	SNJ54HC161W	
	LCCC - FK	Tube of 55	SNJ54HC161FK	SNJ54HC161FK	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SN54HC161, SN74HC161 4-BIT SYNCHRONOUS BINARY COUNTERS

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description/ordering information (continued)

These counters are fully programmable; that is, they can be preset to any number between 0 and 9 or 15. As presetting is synchronous, setting up a low level at the load input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of the enable inputs.

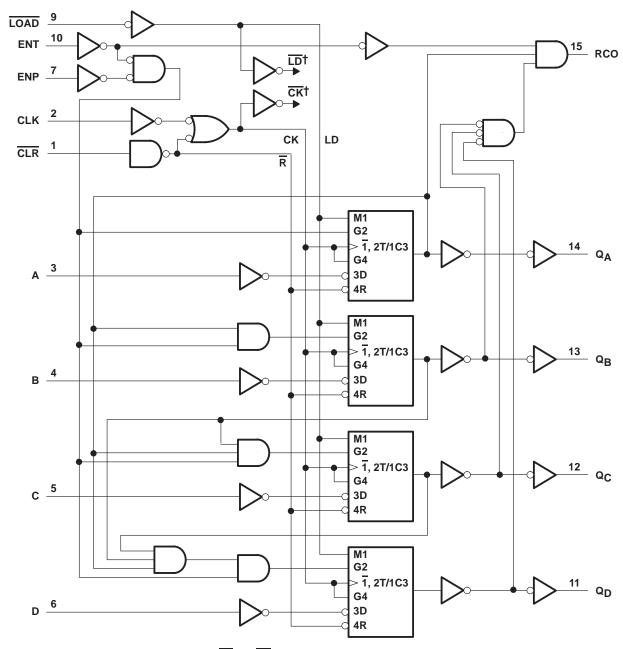
The clear function for the 'HC161 devices is asynchronous. A low level at the clear (CLR) input sets all four of the flip-flop outputs low, regardless of the levels of the CLK, load (LOAD), or enable inputs.

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. Instrumental in accomplishing this function are ENP, ENT, and a ripple-carry output (RCO). Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO. Enabling RCO produces a high-level pulse while the count is maximum (9 or 15 with Q_A high). This high-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.

These counters feature a fully independent clock circuit. Changes at control inputs (ENP, ENT, or $\overline{\text{LOAD}}$) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.



logic diagram (positive logic)

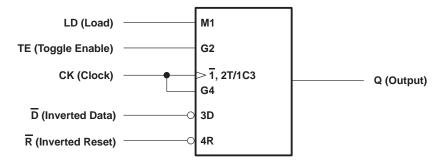


[†] For simplicity, routing of complementary signals \overline{LD} and \overline{CK} is not shown on this overall logic diagram. The uses of these signals are shown on the logic diagram of the D/T flip-flops.

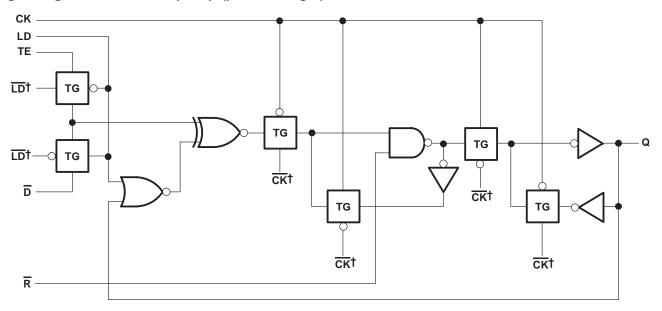
Pin numbers shown are for the D, J, N, NS, PW, and W packages.

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logic symbol, each D/T flip-flop



logic diagram, each D/T flip-flop (positive logic)

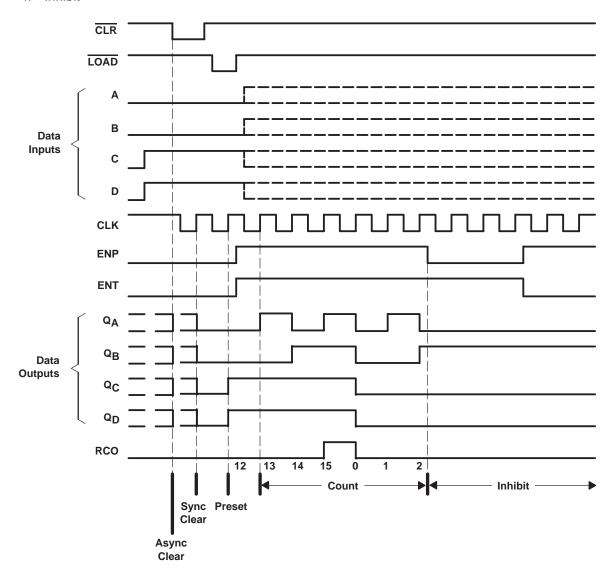


 $^{^\}dagger$ The origins of $\overline{\text{LD}}$ and $\overline{\text{CK}}$ are shown in the logic diagram of the overall device.

typical clear, preset, count, and inhibit sequence

The following sequence is illustrated below:

- 1. Clear outputs to zero (asynchronous)
- 2. Preset to binary 12
- 3. Count to 13, 14, 15, 0, 1, and 2
- 4. Inhibit



SN54HC161, SN74HC161 4-BIT SYNCHRONOUS BINARY COUNTERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}		-0.5	V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (se	ee Note 1)		±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CO}	c) (see Note 1)		±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})			±25 mA
Continuous current through V _{CC} or GND			±50 mA
Package thermal impedance, θ_{JA} (see Note 2):	D package		73°C/W
	N package		67°C/W
	NS package		64°C/W
	PW package	1	108°C/W
Storage temperature range, T _{stg}		65°C 1	to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SI	N54HC16	61	SN	174HC16	1		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage		2	5	6	2	5	6	V	
		V _{CC} = 2 V	1.5			1.5				
٧ _{IH}	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V	
		VCC = 6 V	4.2			4.2				
		V _{CC} = 2 V			0.5			0.5		
٧ _{IL}	V _{II} Low-level input voltage	V _{CC} = 4.5 V			1.35			1.35	V	
		V _{CC} = 6 V			1.8			1.8		
٧ _I	Input voltage		0		VCC	0		VCC	V	
٧o	Output voltage		0		VCC	0		VCC	V	
		V _{CC} = 2 V			1000			1000		
Δt/Δv‡	Input transition rise/fall time	V _{CC} = 4.5 V			500			500	ns	
		V _{CC} = 6 V			400			400		
TA	Operating free-air temperature		-55		125	-40		85	°C	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

[‡] If this device is used in the threshold region (from V_{IL}max = 0.5 V to V_{IH}min = 1.5 V), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at t_t = 1000 ns and V_{CC} = 2 V does not damage the device; however, functionally, the CLK inputs are not ensured while in the shift, count, or toggle operating modes.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555	7507.00	NDITIONS.	.,	Т	A = 25°C	;	SN54H	IC161	SN74HC161		UNIT
PARAMETER	TEST CC	ONDITIONS	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
VOH	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
VOL	VI = VIH or VIL		6 V		0.001	0.1		0.1		0.1	V
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10	_	10	pF

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			\ ,	T _A =	25°C	SN54H	C161	SN74HC161		
			vcc	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		6		4.2		5	
fclock	clock Clock frequency		4.5 V		31		21		25	MHz
			6 V		36		25		29	
			2 V	80		120		100		
		CLK high or low	4.5 V	16		24		20		
	Pulse duration		6 V	14		20		17		ns
t _W	Fulse duration		2 V	80		120		100		115
		CLR low	4.5 V	16		24		20		
			6 V	14		20		17		
			2 V	150		225		190		
		A, B, C, or D	4.5 V	30		45		38		
			6 V	26		38		32		
			2 V	135		205		170		
		LOAD low	4.5 V	27		41		34		
	Saturations hafara CLIV		6 V	23		35		29		
t _{su}	Setup time before CLK↑		2 V	170		255		215		ns
		ENP, ENT	4.5 V	34		51		43		
			6 V	29		43		37		
			2 V	125		190		155		
		CLR inactive	4.5 V	25		38		31		
			6 V	21		32		26		
			2 V	0		0		0		
^t h	th Hold time, all synchronous inputs after CLK↑		4.5 V	0		0		0		ns
			6 V	0		0		0		

SN54HC161, SN74HC161 4-BIT SYNCHRONOUS BINARY COUNTERS

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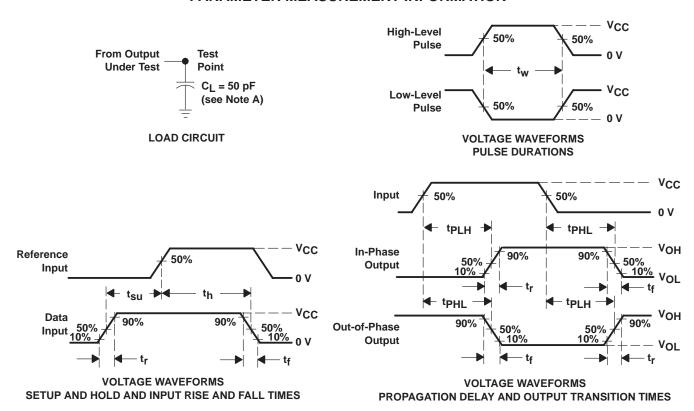
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

24244555	FROM	то	.,	T,	4 = 25°C	;	SN54F	IC161	SN74H	IC161	
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	6	14		4.2		5		
f _{max}			4.5 V	31	40		21		25		MHz
			6 V	36	44		25		29		
			2 V		83	215		325		270	
		RCO	4.5 V		24	43		65		54	
	OLK.		6 V		20	37		55		46	
	CLK		2 V		80	205		310		255	
^t pd		Any Q	4.5 V		25	41		62		51	ns
'			6 V		21	35		53		43	
	ENT	RCO	2 V		62	195		295		245	
			4.5 V		17	39		59		49	
			6 V		14	33		50		42	
			2 V		105	210		315		265	
		Any Q	4.5 V		21	42		63		53	
	CLR		6 V		18	36		54		45	
^t PHL	CLR		2 V		110	220		330		275	ns
		RCO	4.5 V		22	44		66		55	
			6 V		19	37		56		47	
			2 V		38	75		110		95	
t _t		Any	4.5 V		8	15		22		19	ns
			6 V		6	13		19		16	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load	60	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 6 \ ns$, $t_f = 6 \ ns$.
- C. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

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APPLICATION INFORMATION

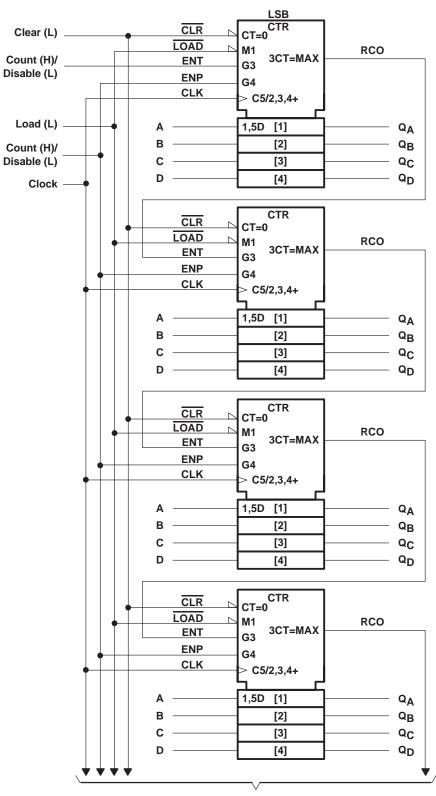
n-bit synchronous counters

This application demonstrates how the look-ahead carry circuit can be used to implement a high-speed n-bit counter. The 'HC161 devices count in binary. Virtually any count mode (modulo-N, N₁-to-N₂, N₁-to-maximum) can be used with this fast look-ahead circuit.

The application circuit shown in Figure 2 is not valid for clock frequencies above 18 MHz (at 25° C and $4.5\text{-V}\ V_{CC}$). The reason for this is that there is a glitch that is produced on the second stage's RCO and every succeeding stage's RCO. This glitch is common to all HC vendors that Texas Instruments has evaluated, in addition to the bipolar equivalents (LS, ALS, AS).



APPLICATION INFORMATION



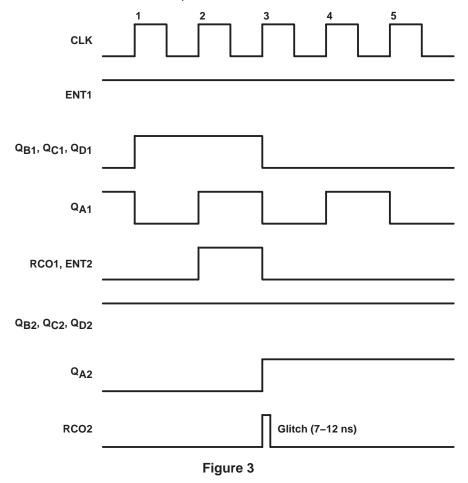
To More-Significant Stages

Figure 2



APPLICATION INFORMATION

The glitch on RCO is caused because the propagation delay of the rising edge of Q_A of the second stage is shorter than the propagation delay of the falling edge of ENT. RCO is the product of ENT, QA, QB, QC, and QD $(ENT \times Q_A \times Q_B \times Q_C \times Q_D)$. The resulting glitch is about 7–12 ns in duration. Figure 3 shows the condition in which the glitch occurs. For simplicity, only two stages are being considered, but the results can be applied to other stages. Q_B , Q_C , and Q_D of the first and second stage are at logic one, and Q_A of both stages are at logic zero (1110 1110) after the first clock pulse. On the rising edge of the second clock pulse, QA and RCO of the first stage go high. On the rising edge of the third clock pulse, QA and RCO of the first stage return to a low level, and QA of the second stage goes to a high level. At this time, the glitch on RCO of the second stage appears because of the race condition inside the chip.



The glitch causes a problem in the next stage (stage three) if the glitch is still present when the next rising clock edge appears (clock pulse 4). To ensure that this does not happen, the clock frequency must be less than the inverse of the sum of the clock-to-RCO propagation delay and the glitch duration (ta). In other words, $f_{max} = 1/(t_{pd} CLK-to-RCO + t_g)$. For example, at 25°C at 4.5-V V_{CC} , the clock-to-RCO propagation delay is 43 ns and the maximum duration of the glitch is 12 ns. Therefore, the maximum clock frequency that the cascaded counters can use is 18 MHz. The following tables contain the f_{clock}, t_w, and f_{max} specifications for applications that use more than two 'HC161 devices cascaded together.

APPLICATION INFORMATION

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		.,	T _A = 25°C		SN54HC161		SN74HC161		LINIT
		VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
		2 V		3.6		2.5		2.9	
f _{clock} Clock frequency	Clock frequency	4.5 V		18		12		14	MHz
		6 V		21		14		17	
		2 V	140		200		170		
t _W	Pulse duration, CLK high or low	4.5 V	28		40		36		ns
		6 V	24		36		30		

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Note 4)

24244555	FROM	то	.,	T _A = 25°C		SN54HC161		SN74HC161		
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	3.6		2.5		2.9		
f _{max}			4.5 V	18		12		14		MHz
			6 V	21		14		17		

NOTE 4: These limits apply only to applications that use more than two 'HC161 devices cascaded together.

If the 'HC161 devices are used as a single unit, or only two cascaded together, then the maximum clock frequency that the device can use is not limited because of the glitch. In these situations, the device can be operated at the maximum specifications.

A glitch can appear on RCO of a single 'HC161 device, depending on the relationship of ENT to CLK. Any application that uses RCO to drive any input except an ENT of another cascaded 'HC161 device must take this into consideration.







PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
84075012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
8407501EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
8407501FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/66302BEA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
JM38510/66302BFA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SN54HC161J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN74HC161D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161DBR	OBSOLETE	SSOP	DB	16		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161DT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161DTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC161N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74HC161NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74HC161NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161PWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC161PWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54HC161FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54HC161J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54HC161W	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.



PACKAGE OPTION ADDENDUM

17-Oct-2005

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

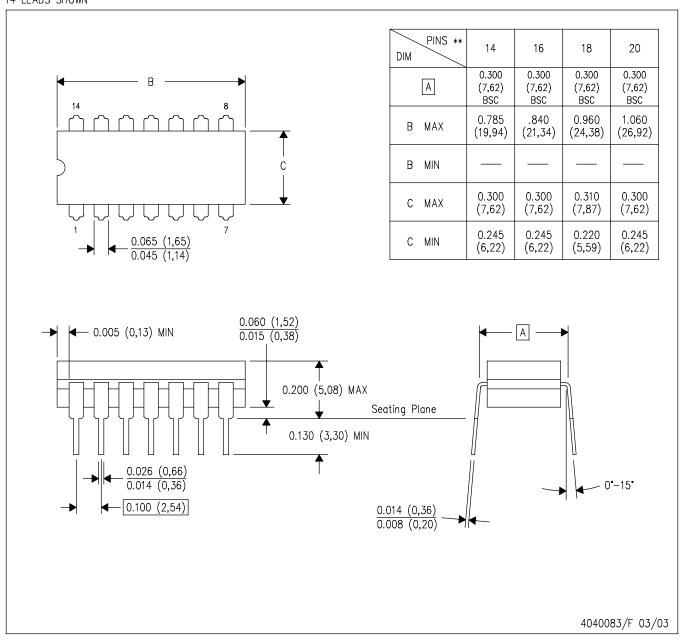
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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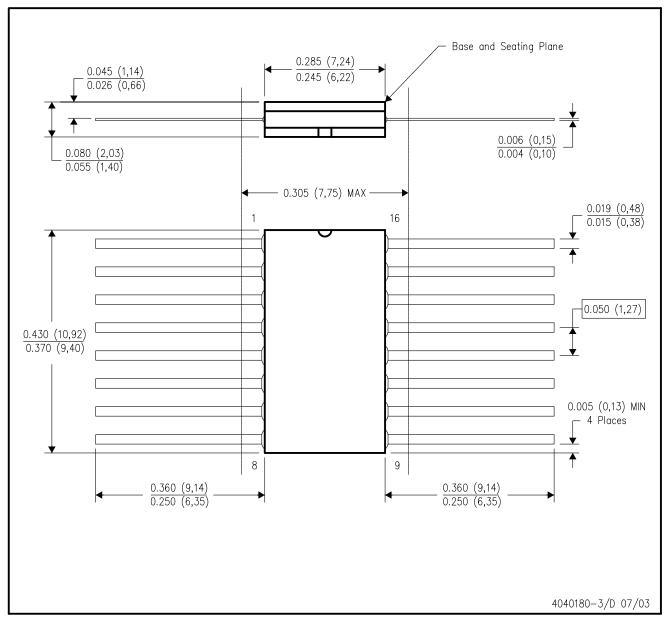
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



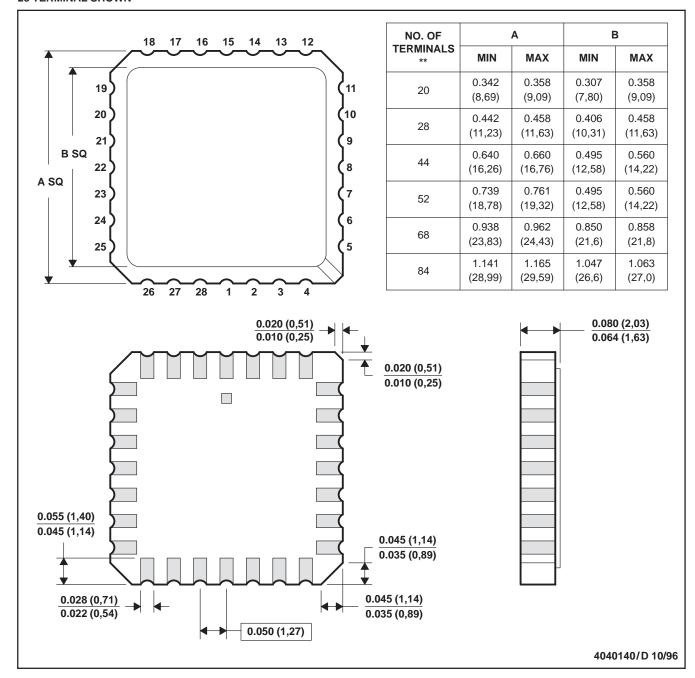
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

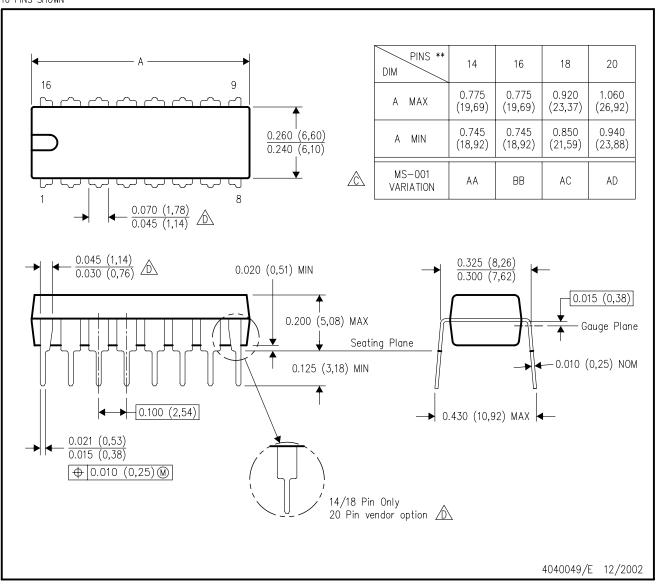
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

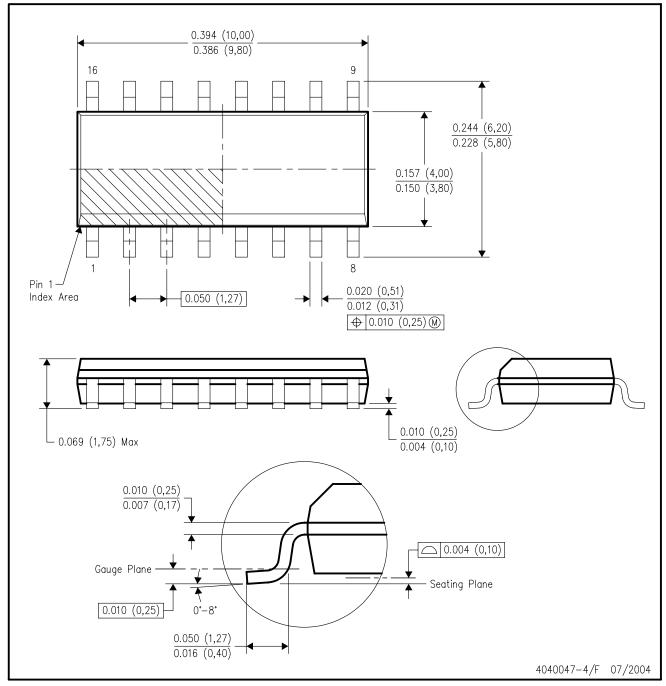


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.

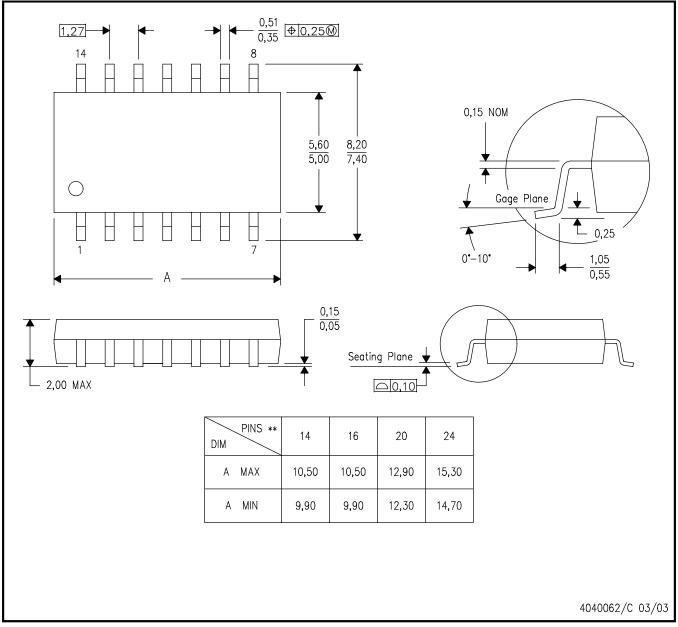


MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



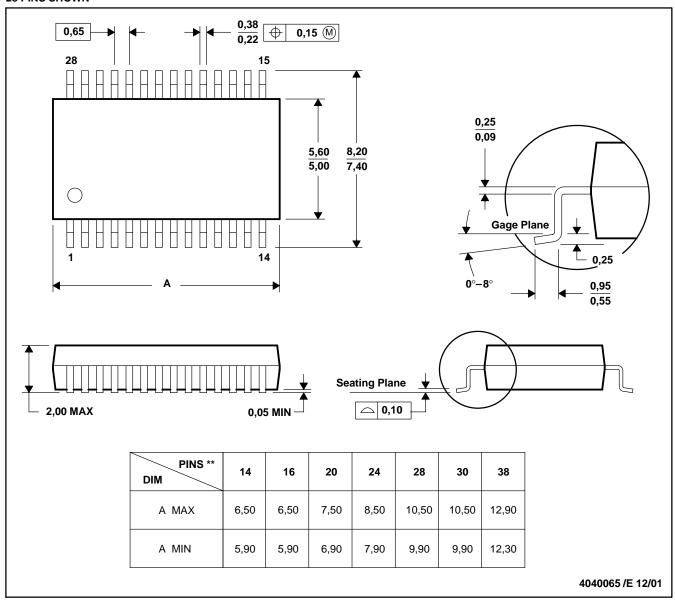
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

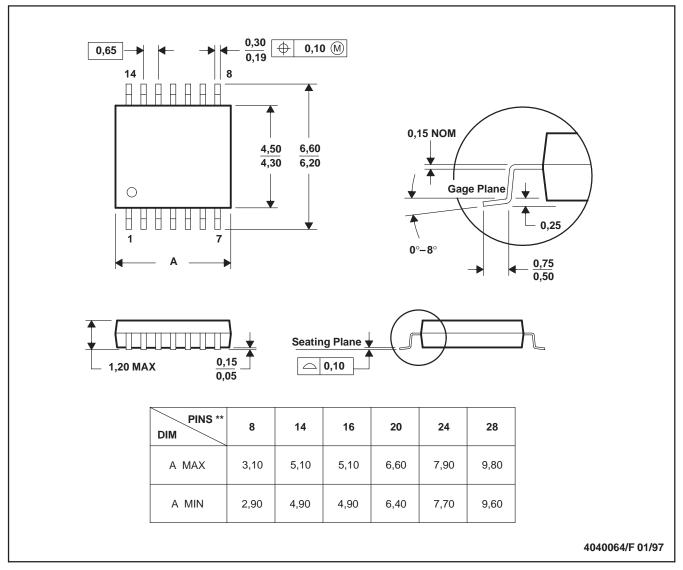
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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